

Title (en)

METHOD FOR ESTABLISHING AN ELECTRICAL AND MECHANICAL CONNECTION BETWEEN CHIP CONTACT SURFACES AND ANTENNA CONTACT SURFACES AND TRANSPONDER

Title (de)

VERFAHREN ZUM ELEKTRISCHEN UND MECHANISCHEN VERBINDEN VON CHIPANSCHLUSSFLÄCHEN MIT ANTENNENANSCHLUSSFLÄCHEN UND TRANSPONDER

Title (fr)

PROCEDE POUR ETABLIR UNE LIAISON ELECTRIQUE ET MECANIQUE ENTRE DES PASTILLES DE PUCE ET DES PASTILLES D'ANTENNE ET TRANSPONDEUR

Publication

**EP 1856729 A1 20071121 (DE)**

Application

**EP 06724965 A 20060308**

Priority

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- DE 102005016930 A 20050413

Abstract (en)

[origin: DE102005016930A1] The method involves hooking contact surfaces (11, 12) of a chip, having a set of wire-shaped hooks/lugs (13) on their surfaces, with contact surfaces (19, 20) of a strip substrate, having a set of hooks/ lugs (16) on their surfaces, by applying pressure on the surfaces (19, 20). An RFID antenna is arranged on the substrate. Electrically conducting wires are used as a material for the hooks/lugs with a size in a nanometer range.

IPC 8 full level

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Citation (search report)

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Citation (examination)

US 2003136503 A1 20030724 - GREEN ALAN [US], et al

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